

OCT 25 2005

Patent

Docket No. MTI-31607

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Lee, Teck et al.  
Serial No. : 10/050,507  
Filing Date : January 16, 2002  
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking  
Examiner : THOMPSON, Craig  
Confirmation No. : 7687  
Group Art Unit : 2813

---

**CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10**

I hereby certify that, on the date shown below, this correspondence is being transmitted to Fax No. 571-273-8300 addressed to Examiner THOMPSON at the US Patent and Trademark Office.

Date: \_\_\_\_\_

---

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**STATUS INQUIRY**

Dear Sir:

This application was filed on January 16, 2002, and the last correspondence filed in this application is a Request for Continued Examination (RCE) submitted May 10, 2005.

More than fifty-seven (57) months (from the filing date), and five (5) months (from the mailing date of the RCE) have passed without receiving any communication from the U.S. Patent and Trademark Office. Please provide us with a status of this application.

Respectfully submitted,

Dated: October 25, 2005

Kristine M. Strodthoff  
Kristine M. Strodthoff  
Registration No. 34259

**P.O. ADDRESS:**

WHYTE HIRSCHBOECK DUDEK S.C.  
555 East Wells Street, Suite 1900  
Milwaukee, Wisconsin 53202-3819  
(414) 273-2100  
Customer No. 31870

MKE/896969.2